PRODUCT CHANGE NOTICE				
PART NUMBER(S):	PCN No.: 06-0130-16a			
Please see attachment.	DATE: June 23, 2006			
PART DESCRIPTION:				
Power Management and Interface Products – Change in Wafer Fabrication Site				
LEVEL OF CHANGE:				
[X] Level I, Customer Approval.	[] Level II, Customer Information.			
PRODUCT ATTRIBUTE AFFECTED:				
[] Material Change [] Design Change [X] Process Change	Data Sheet Change Package Change Packing / Shipping			
[X] Other, Explain: Wafer Fabrication Site Transfer				
DESCRIPTION OF CHANGE:				
Announcing transfer of certain Power Management and Interface Products from Hillview wafer fabrication facility to wafer foundry EPISIL. See attached Product List no. 16a.				
REASON FOR CHANGE:				
Power Management and Interface products as listed are being transferred to external wafer foundry, due to cessation of operations of the Sipex Hillview Wafer Fabrication manufacturing site.				

FABRICATION PROCESS QUALIFICATION

COMPLETED (DATE): November 25, 2006

PRODUCT CHARACTERIZATION COMPLETED AND

SAMPLES* AVAILABLE (DATE): December 2, 2006

^{*} Samples representative of product from the Product Family being transferred.



PRODUCT CHANGE NOTICE				
EARLIEST DATE OF PRODUCTIO SHIPMENTS: January 31, 2007	N			
EFFECTIVITY CHANGE DATE OR	DATE CODE:	Work week associa	ated wit	h earliest production shipment.
[] STANDARD DISTRIBUTION			[X]	CUSTOM DISTRIBUTION
PERSON TO CONTACT WITH QUI	ESTIONS:			
Fred Claussen				
VP Quality Assurance and Reliability Sipex Corporation Phone Number: 408-935-7644 FAX NUMBER: 408-935-7678	,			



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List 16a

SP331CT SP331CT-L SP331ET SP331ET-L